



Vincotech

V23990-P629-F48-PM
datasheet

fastPACK 0

1200 V / 40 A

Features

- Low inductance layout
- Clip-in PCB mounting

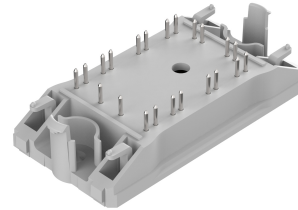
Target applications

- Charging Stations
- Power Supply
- UPS
- Welding & Cutting

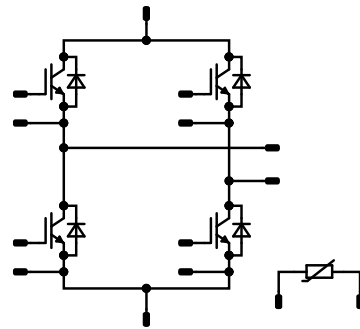
Types

- V23990-P629-F48-PM

flow 0 12 mm housing



Schematic





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Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
H-Bridge Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	44	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	120	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	113	W
Gate-emitter voltage	V_{GES}		±20	V
Short circuit ratings	t_{SC}	$V_{GE} = 15\text{ V}$, $V_{CC} = 800\text{ V}$ $T_j = 150\text{ °C}$	10	µs
Maximum junction temperature	T_{jmax}		175	°C

H-Bridge Diode

Peak repetitive reverse voltage	V_{RRM}		1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	24	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	100	A
Surge current capability	I^2t		50	A²s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	61	W
Maximum junction temperature	T_{jmax}		175	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
Isolation voltage	V_{isol}	AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance			>12,7	mm
Clearance			9,55	mm
Comparative Tracking Index	CTI		≥ 200	

*100 % tested in production



Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

H-Bridge Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0015	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		40	25 125	1,78	1,96 2,29	2,42 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			5	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	$f = 1 \text{ Mhz}$	0	25	25			2330		pF
Output capacitance	C_{oes}							150		pF
Reverse transfer capacitance	C_{res}							130		pF
Gate charge	Q_g	$V_{CC} = 960 \text{ V}$	15		40	25		185		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4 \text{ W/mK}$ (PSX)						0,84		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 8 \Omega$ $R_{goff} = 8 \Omega$	± 15	600	40	25 125 150		63,6 65 66		ns
Rise time	t_r					25 125 150		15,4 18,6 18		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		162,4 215,8 229,6		ns
Fall time	t_f					25 125 150		26,3 62,8 70,15		ns
Turn-on energy (per pulse)	E_{on}	$Q_{tFWD}=2,7 \mu\text{C}$ $Q_{tFWD}=4,78 \mu\text{C}$ $Q_{tFWD}=5,82 \mu\text{C}$				25 125 150		1,54 2,19 2,41		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		1,32 2,29 2,53		mWs



Characteristic Values

Parameter	Symbol	Conditions						Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]		Min	Typ	Max	

H-Bridge Diode

Static

Forward voltage	V_F				25	25 150		2,47 2,49	2,74 ⁽¹⁾ 2,79 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1200$ V				25 150			60 3300	µA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,56		K/W
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Dynamic

Peak recovery current	I_{RRM}	$di/dt=3019$ A/µs $di/dt=3104$ A/µs $di/dt=2972$ A/µs	± 15	600	40	25 125 150		48,06 54,99 60,27		A
Reverse recovery time	t_{rr}					25 125 150		101,42 221,81 250,67		ns
Recovered charge	Q_r					25 125 150		2,7 4,78 5,82		µC
Reverse recovered energy	E_{rec}					25 125 150		1,13 2,11 2,6		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		3780 2583 2658		A/µs



Characteristic Values

Parameter	Symbol	Conditions						Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Thermistor

Static

Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1486 \Omega$				100	-12		14	%
Power dissipation	P							200		mW
Power dissipation constant	d					25		2		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 3 \%$						3950		K
B-value	$B_{(25/100)}$	Tol. $\pm 3 \%$						3998		K
Vincotech Thermistor Reference									B	

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.



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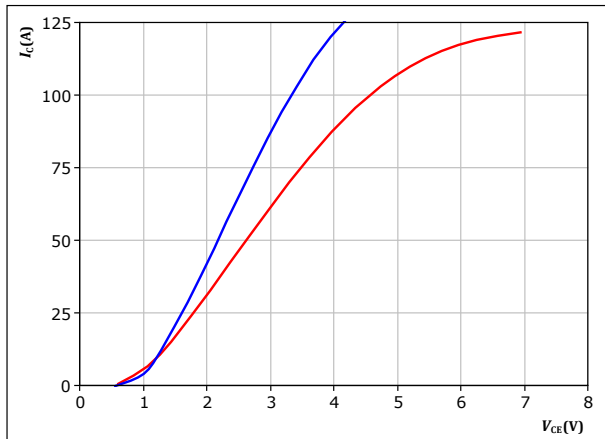
V23990-P629-F48-PM
datasheet

H-Bridge Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

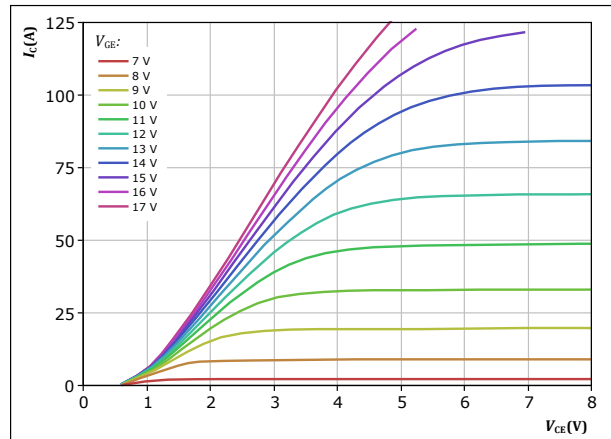


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_J: 25 ^\circ C$ (blue line)
 $125 ^\circ C$ (red line)

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

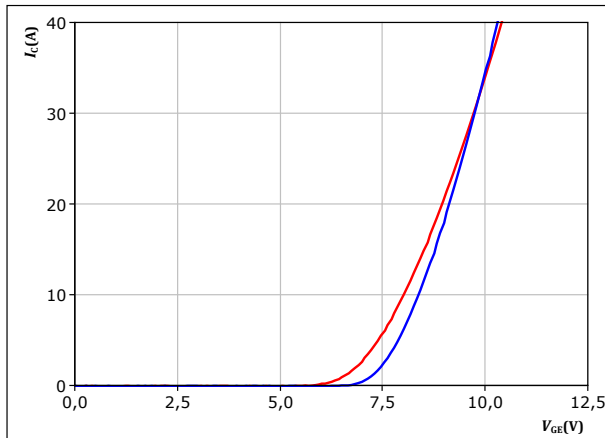


$t_p = 250 \mu s$
 $T_J = 125 ^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

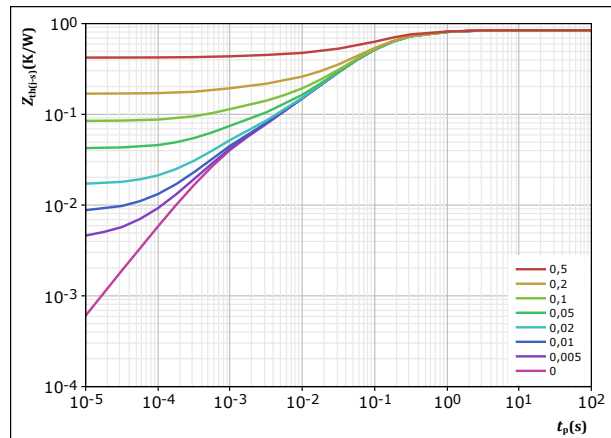


$t_p = 250 \mu s$
 $V_{CE} = 10 V$
 $T_J: 25 ^\circ C$ (blue line)
 $125 ^\circ C$ (red line)

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,844 K/W$
IGBT thermal model values

$R (K/W)$	$\tau (s)$
1,18E-01	8,20E-01
4,24E-01	1,32E-01
2,01E-01	4,79E-02
6,46E-02	9,26E-03
3,72E-02	8,03E-04



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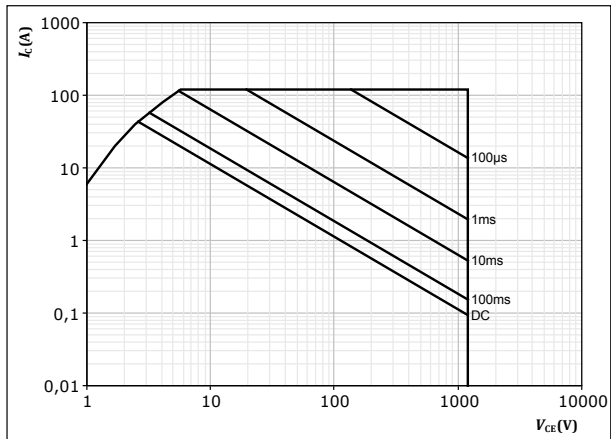
H-Bridge Switch Characteristics

figure 5.

IGBT

Safe operating area

$I_C = f(V_{CE})$



$D = \text{single pulse}$

$T_s = 80 \text{ } ^\circ\text{C}$
 $V_{GE} = 15 \text{ V}$
 $T_j = T_{jmax}$



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H-Bridge Diode Characteristics

figure 6. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

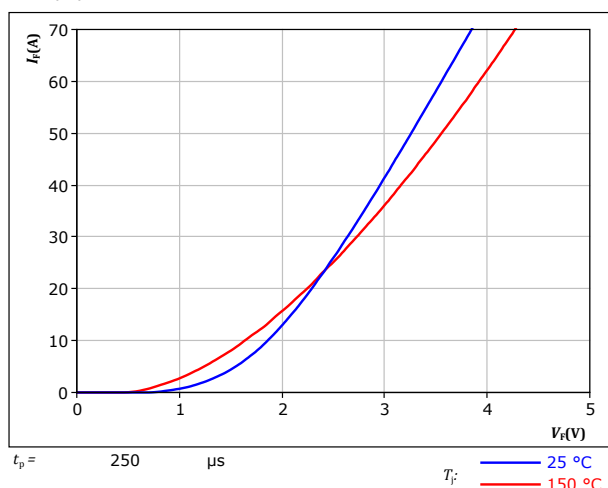
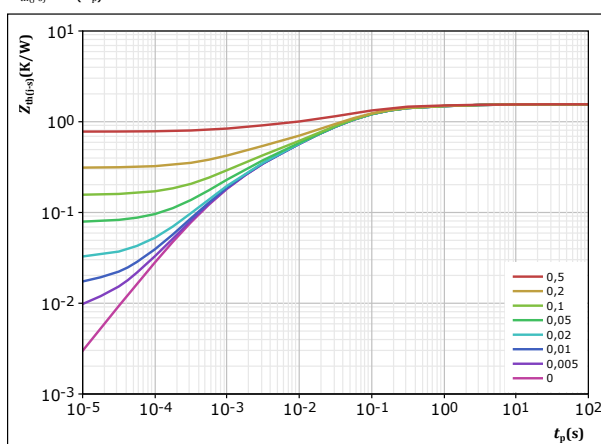


figure 7. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D =$	t_p / T	
$R_{th(j-s)} =$	1,556	K/W
FWD thermal model values		
R (K/W)	τ (s)	
4,65E-02	4,86E+00	
1,06E-01	8,11E-01	
4,71E-01	1,09E-01	
4,83E-01	3,07E-02	
2,34E-01	7,03E-03	
1,81E-01	1,25E-03	
3,38E-02	3,28E-04	



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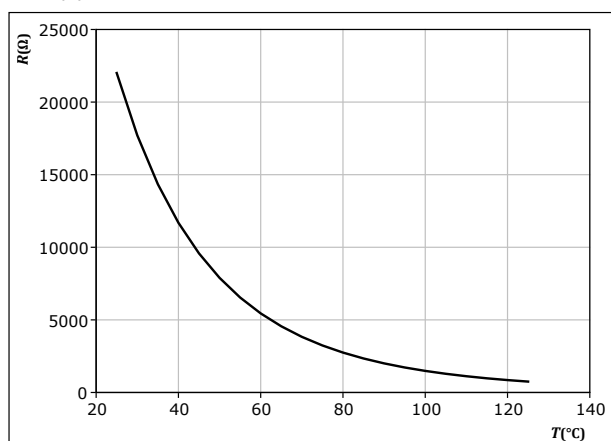
Thermistor Characteristics

figure 8.

Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$





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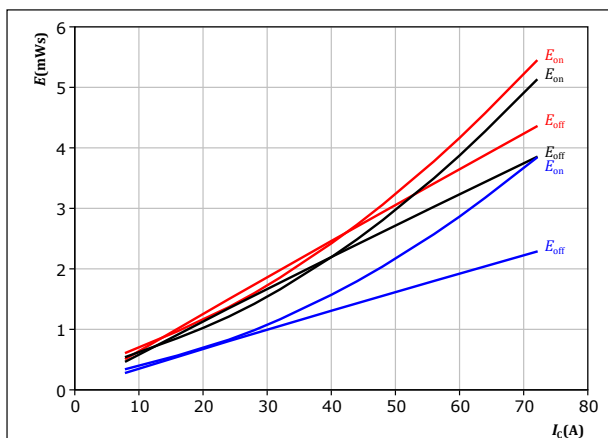
H-Bridge Switching Characteristics

figure 9.

IGBT

Typical switching energy losses as a function of collector current

$$E = f(I_C)$$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$
 $R_{goff} = 8 \text{ } \Omega$

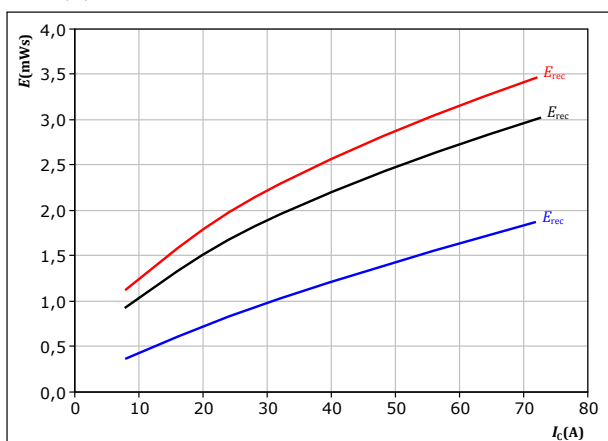
T_j : 25 °C
125 °C
150 °C

figure 11.

FWD

Typical reverse recovered energy loss as a function of collector current

$$E_{rec} = f(I_C)$$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$

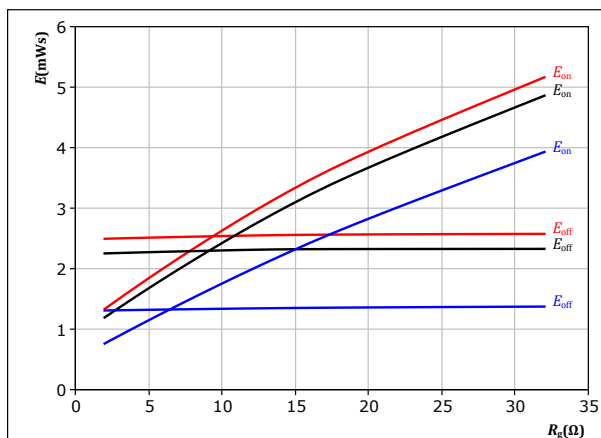
T_j : 25 °C
125 °C
150 °C

figure 10.

IGBT

Typical switching energy losses as a function of gate resistor

$$E = f(R_g)$$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 40 \text{ A}$

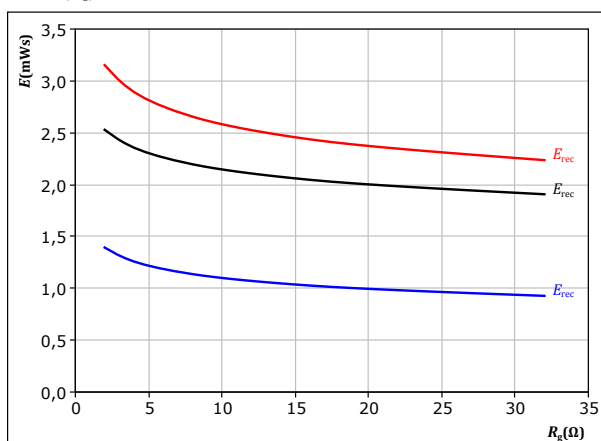
T_j : 25 °C
125 °C
150 °C

figure 12.

FWD

Typical reverse recovered energy loss as a function of gate resistor

$$E_{rec} = f(R_g)$$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 40 \text{ A}$

T_j : 25 °C
125 °C
150 °C



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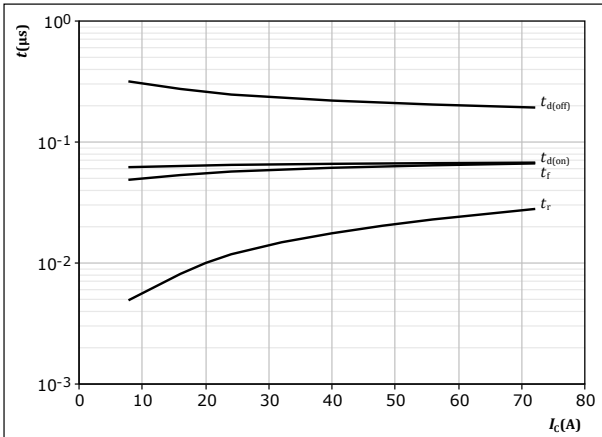
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datasheet

H-Bridge Switching Characteristics

figure 13.

IGBT

Typical switching times as a function of collector current
 $t = f(I_C)$



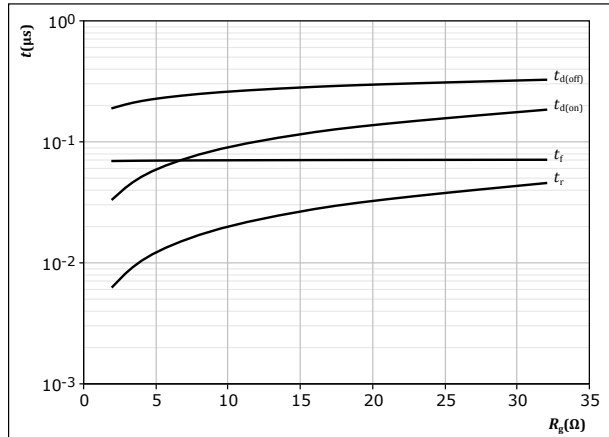
With an inductive load at

$T_j = 150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω
 $R_{goff} = 8$ Ω

figure 14.

IGBT

Typical switching times as a function of gate resistor
 $t = f(R_g)$



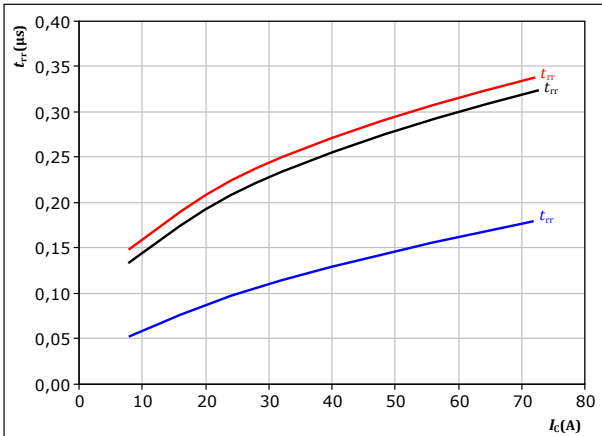
With an inductive load at

$T_j = 150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 40$ A

figure 15.

FWD

Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_C)$



With an inductive load at

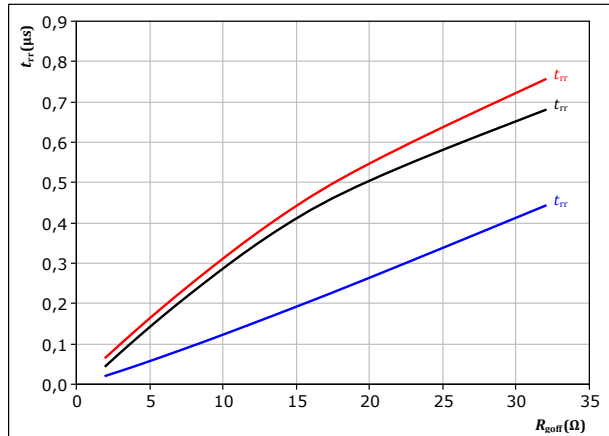
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω

T_j : — 25 °C
— 125 °C
— 150 °C

figure 16.

FWD

Typical reverse recovery time as a function of IGBT turn off gate resistor
 $t_{rr} = f(R_{goff})$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 40$ A

T_j : — 25 °C
— 125 °C
— 150 °C



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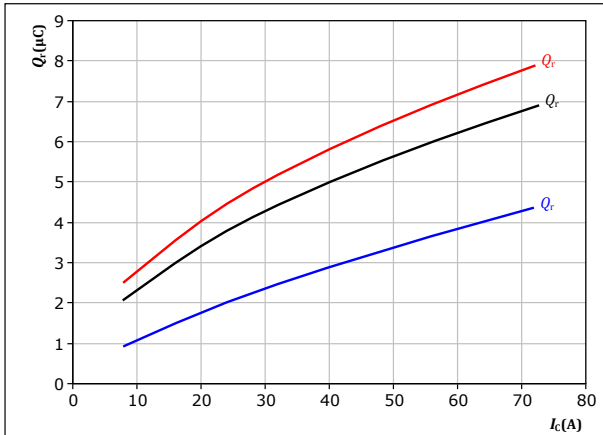
H-Bridge Switching Characteristics

figure 17.

FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω

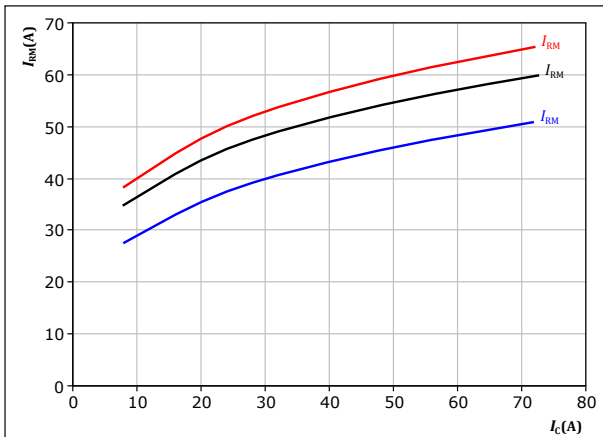
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 19.

FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω

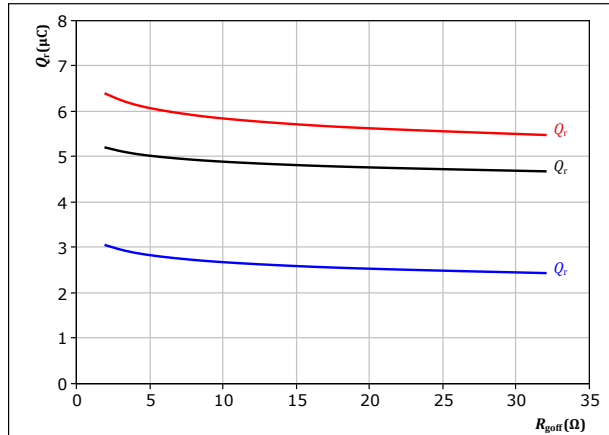
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 18.

FWD

Typical recovered charge as a function of turn off gate resistor

$$Q_r = f(R_{goff})$$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 40$ A

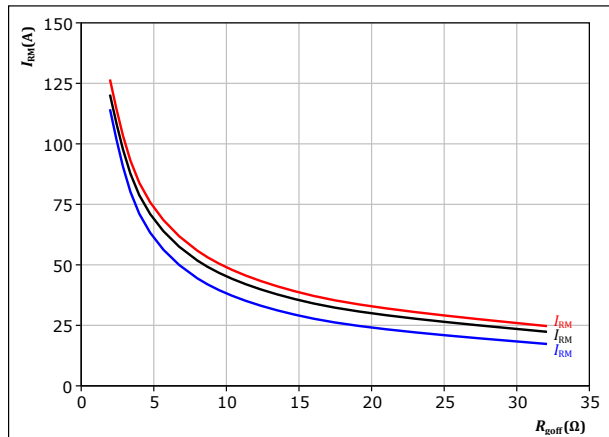
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 20.

FWD

Typical peak reverse recovery current as a function of turn off gate resistor

$$I_{RM} = f(R_{goff})$$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 40$ A

T_j :
— 25 °C
— 125 °C
— 150 °C



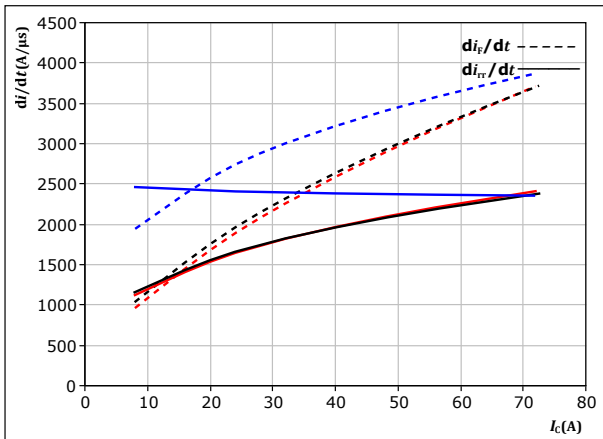
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H-Bridge Switching Characteristics

figure 21. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_r/dt = f(I_C)$



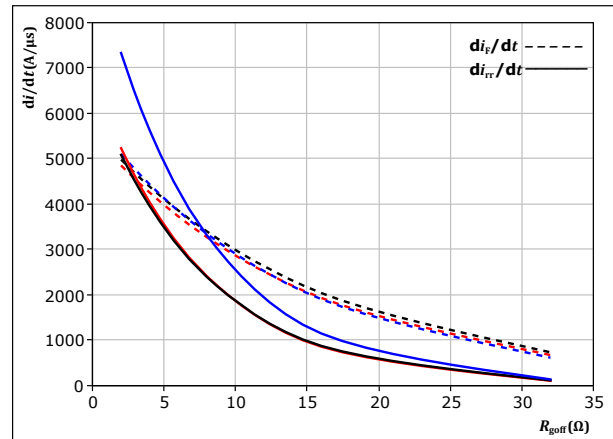
With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{goff} = 8 \text{ } \Omega$

$T_j = 25 \text{ } ^\circ\text{C}$
 $T_j = 125 \text{ } ^\circ\text{C}$
 $T_j = 150 \text{ } ^\circ\text{C}$

figure 22. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn off gate resistor
 $di_f/dt, di_r/dt = f(R_{goff})$



With an inductive load at

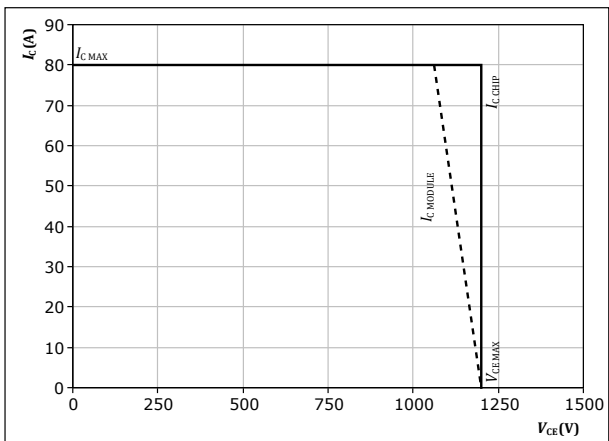
$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 40 \text{ A}$

$T_j = 25 \text{ } ^\circ\text{C}$
 $T_j = 125 \text{ } ^\circ\text{C}$
 $T_j = 150 \text{ } ^\circ\text{C}$

figure 23. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At $T_j = 150 \text{ } ^\circ\text{C}$
 $R_{goff} = 8 \text{ } \Omega$
 $R_{goff} = 8 \text{ } \Omega$



H-Bridge Switching Definitions

figure 24. IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

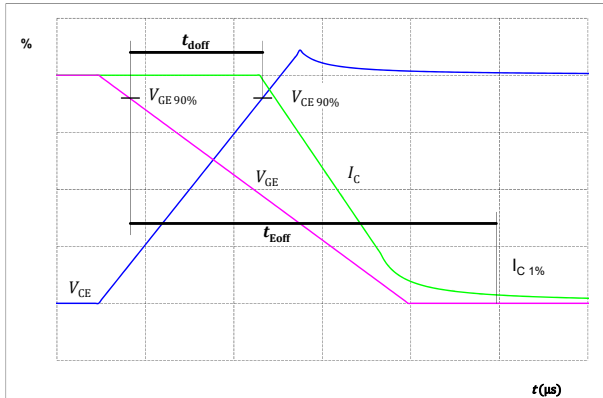


figure 25. IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

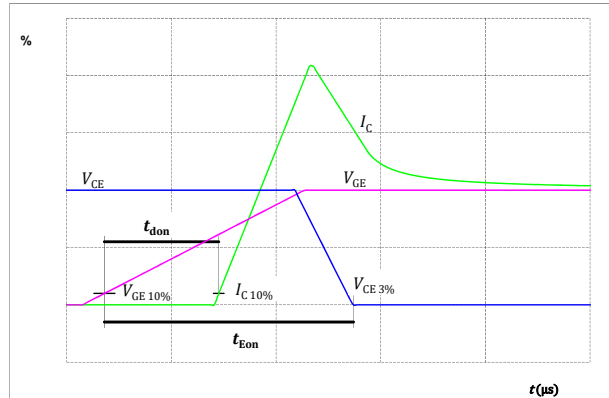


figure 26. IGBT

Turn-off Switching Waveforms & definition of t_f

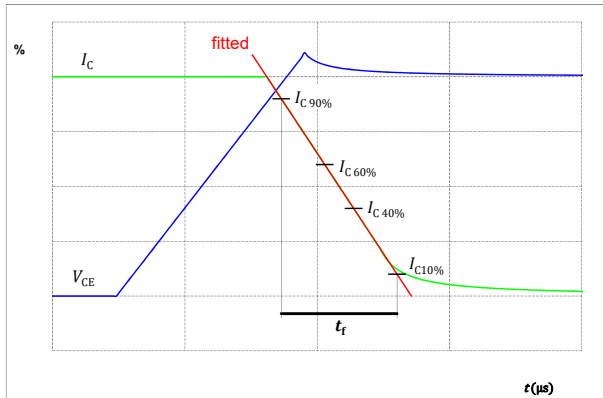
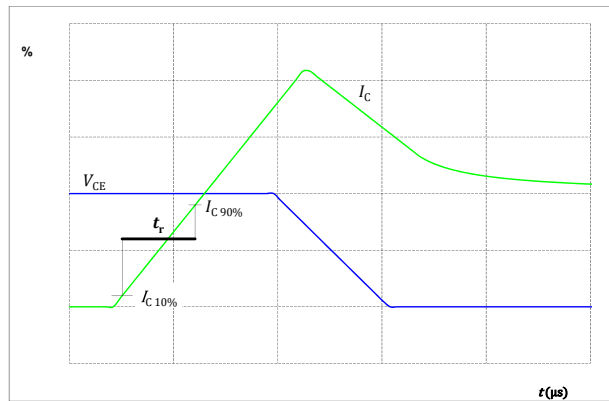


figure 27. IGBT

Turn-on Switching Waveforms & definition of t_r





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H-Bridge Switching Definitions

figure 28.

FWD

Turn-off Switching Waveforms & definition of t_{rr}

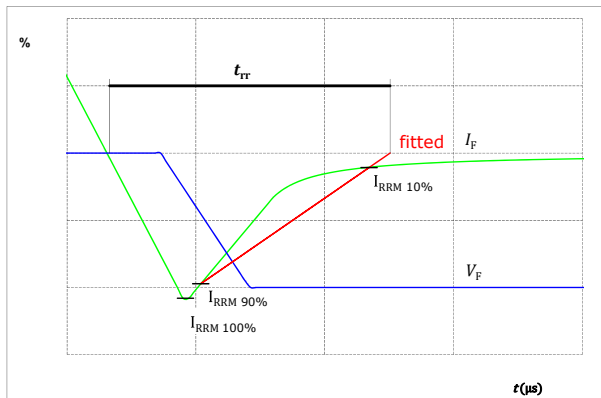
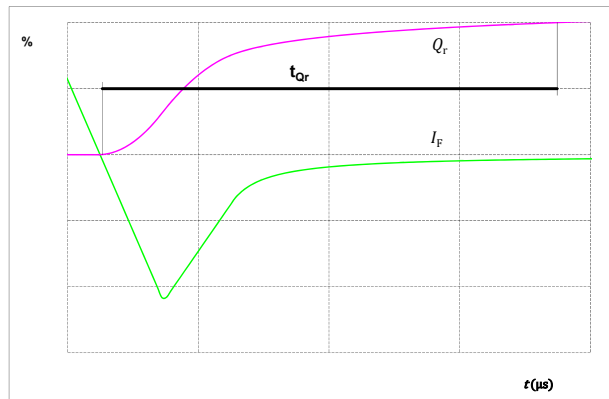


figure 29.

FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)





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V23990-P629-F48-PM

datasheet

Ordering Code	
Version	Ordering Code
Without thermal paste	V23990-P629-F48-PM
With thermal paste (5,2 W/mK, PTM6000HV)	V23990-P629-F48-/7/-PM
With thermal paste (3,4 W/mK, PSX-P7)	V23990-P629-F48-/3/-PM

Marking							
	Text	VIN	Date code	Type&Ver	UL	Lot	Serial
		VIN	WWYY	TTTTTTVV	UL	LLLL	SSSS
	Datamatrix	Type&Ver	Lot number	Serial	Date code		
		TTTTTTVV	LLLL	SSSS	WWYY		

Outline

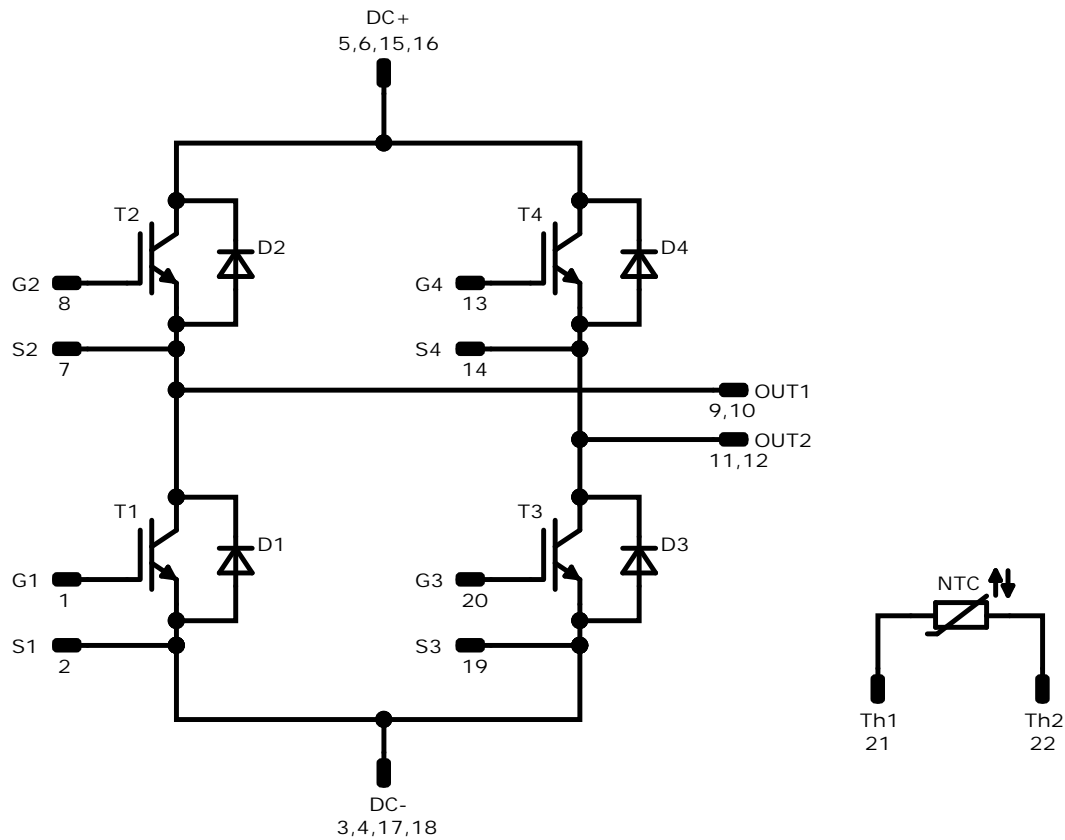
Pin table [mm]			
Pin	X	Y	Function
1	0	22,5	G1
2	2,9	22,5	S1
3	8,3	22,5	DC-
4	10,8	22,5	DC-
5	19,6	22,5	DC+
6	22,1	22,5	DC+
7	29,1	22,5	S2
8	32	22,5	G2
9	33,5	17,8	OUT1
10	33,5	15,3	OUT1
11	33,5	7,2	OUT2
12	33,5	4,7	OUT2
13	32	0	G4
14	29,1	0	S4
15	22,1	0	DC+
16	19,6	0	DC+
17	10,8	0	DC-
18	8,3	0	DC-
19	2,9	0	S3
20	0	0	G3
21	0	8	Th1
22	0	14,5	Th2

Tolerance of pinpositions: ± 0.5 mm at the end of pins
Dimension of coordinate axis is only offset without tolerance



Vincotech


Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T1, T2, T3, T4	IGBT	1200 V	40 A	H-Bridge Switch	
D2, D1, D4, D3	FWD	1200 V	25 A	H-Bridge Diode	
NTC	Thermistor			Thermistor	



Packaging instruction				
Standard packaging quantity (SPQ) 135	>SPQ	Standard	<SPQ	Sample
Handling instruction				
Handling instructions for <i>flow 0</i> packages see vincotech.com website.				
Package data				
Package data for <i>flow 0</i> packages see vincotech.com website.				
Vincotech thermistor reference				
See Vincotech thermistor reference table at vincotech.com website.				
UL recognition and file number				
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.				

Document No.:	Date:	Modification:	Pages
V23990-P629-F48-PM-D2-14	18 Sep. 2021	New Datasheet format, module is unchanged Correct Thermal values of H-Bridge Diode	

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.